INVESTOR PRESENTATION
Q1-26 RESULTS

April 23, 2026

Safe Harbor Statement

This presentation contains statements about management's future expectations, plans and prospects of our business that constitute forward-looking statements, which are found in various places throughout the presentation, including, but not limited to, statements relating to expectations of orders, net sales, product shipments, expenses, timing of purchases of assembly equipment by customers, gross margins, operating results and capital expenditures. The use of words such as “anticipate”, “estimate”, “expect”, “can”, “intend”, “believes”, “may”, “plan”, “predict”, “project”, “forecast”, “will”, “would”, and similar expressions are intended to identify forward-looking statements, although not all forward-looking statements contain these identifying words. In addition, the financial guidance set forth under the heading “Outlook” contains forward-looking statements. While these forward-looking statements represent our judgments and expectations concerning the development of our business, a number of risks, uncertainties and other important factors could cause actual developments and results to differ materially from those contained in forward-looking statements, including any inability to maintain continued demand for our products; failure of anticipated orders to materialize or postponement or cancellation of orders, generally without charges; the volatility in the demand for semiconductors and our products and services; the adverse impacts on the global economy, financial markets, global supply chains and our operations as well as those of our customers and suppliers arising from the COVID-19 pandemic ; failure to develop new and enhanced products and introduce them at competitive price levels; failure to adequately manage costs and expenses in line with revenue; loss of significant customers, including through industry consolidation or the emergence of industry alliances; lengthening of the sales cycle; acts of terrorism and violence; disruption or failure of our information technology systems; consolidation activity and industry alliances in the semiconductor industry that may result in further increased customer concentration, inability to forecast demand and inventory levels for our products; the integrity of product pricing and protection of our intellectual property in foreign jurisdictions; risks, such as changes in trade regulations, conflict minerals regulations, currency fluctuations, political instability and war, associated with substantial foreign customers, suppliers and foreign manufacturing operations, particularly to the extent occurring in the Asia Pacific region where we have a substantial portion of our production facilities; potential instability in foreign capital markets; the risk of failure to successfully manage our diverse operations; any inability to attract and retain skilled personnel, including as a result of restrictions on immigration, travel or the availability of visas for skilled technology workers; and the other risks detailed in the Risk Management section of our Annual Report. We expressly disclaim any obligation to update or alter these forward-looking statements for revisions or changes whether as a result of new information, future events or otherwise after the date of this release.

In addition, the United States and other countries have recently levied tariffs and taxes on certain goods and could significantly increase or impose new tariffs on a broad array of goods. They have imposed, and may continue to impose, new trade restrictions and export regulations. Increased or new tariffs and additional taxes, including any retaliatory measures, trade restrictions and export regulations, could negatively impact end-user demand and customer investment in semiconductor equipment, increase Besi’s supply chain complexity and manufacturing costs, decrease margins, reduce the competitiveness of our products or restrict our ability to sell products, provide services or purchase necessary equipment and supplies. Any or all of the foregoing factor could have a material and adverse effect on our business, results of operations or financial condition. In addition, investors should consider those additional risk factors set forth in Besi's annual report for the year ended December 31, 2025, and other key factors that could adversely affect our businesses and financial performance contained in our filings and reports, including our statutory consolidated statements. We expressly disclaim any obligation to update or alter our forward-looking statements whether as a result of new information, future events or otherwise.

Table of Contents

I. KEY HIGHLIGHTS

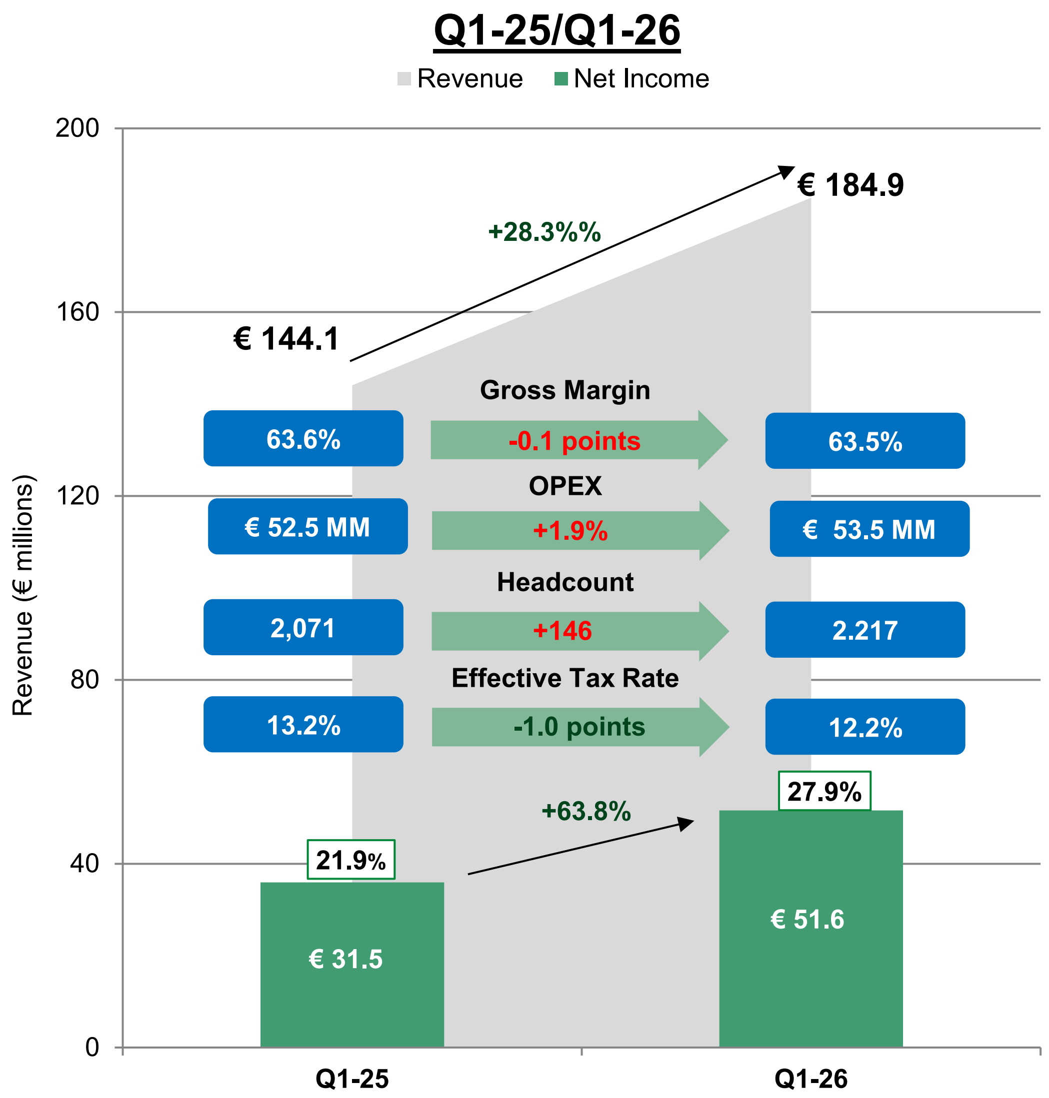
Strong Q1-26 Financial Performance. Order Momentum Continues

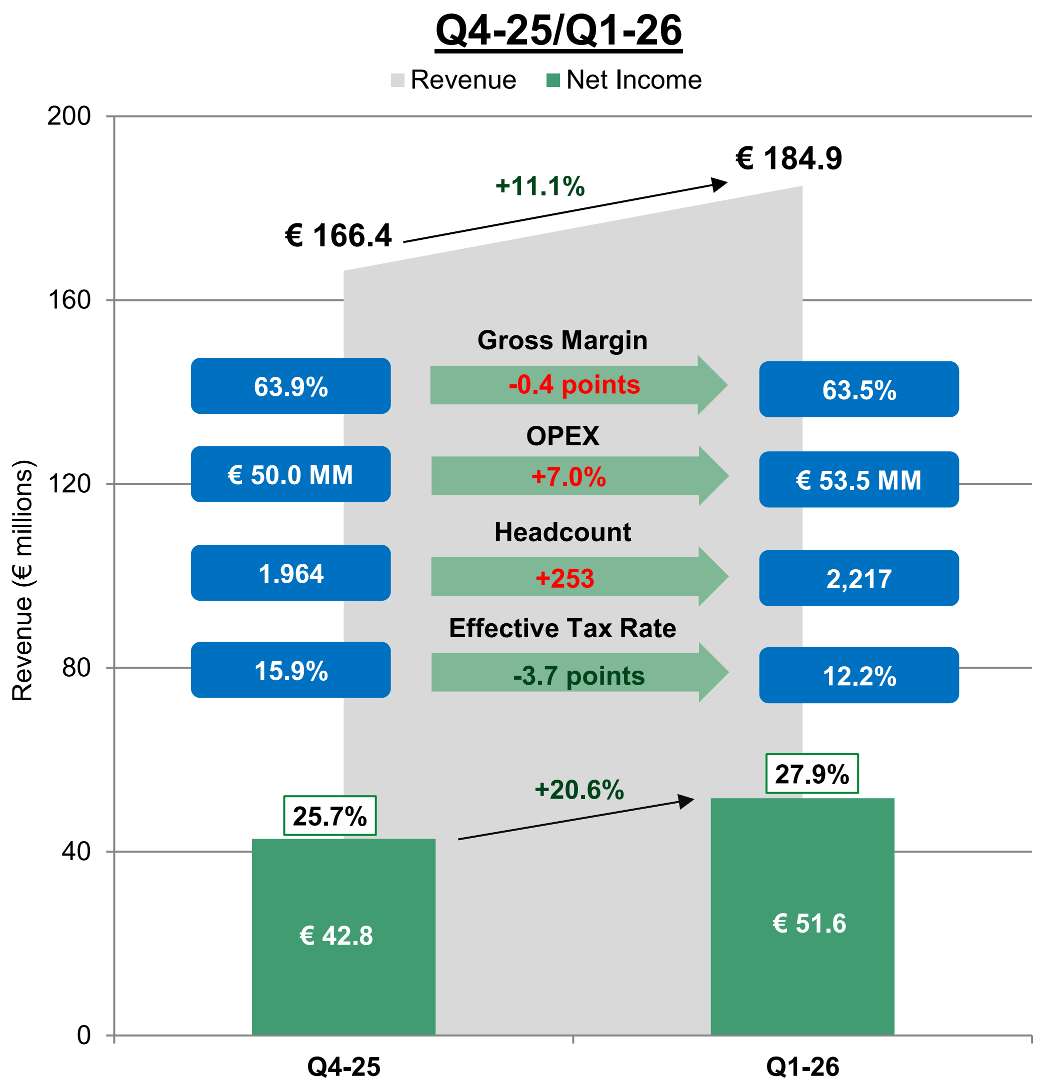
Besi

€ millions	Guidance Q1-26*	Q1-26	Δ *Q4-25*	Δ *Q1-25*
Revenue	Up 5-15%	**184.9**	+11.1%	+28.3%
Orders	Significant increase	**269.7**	+7.7%	+104.5%
Gross Margin	63-65%	**63.5%**	-0.4pts	-0.1pts
Opex	Up 10-15%	**53.5**	+7.0%	+1.9%
Operating Income		**63.9**	+13.7%	+62.6%
EBITDA		**73.7**	+11.5%	+58.2%
Net Income		**51.6**	+20.6%	+63.8%
EPS Basic		**0.65**	+20.4%	+62.5%
Net Cash		**103.3**	+67.3	-56.1

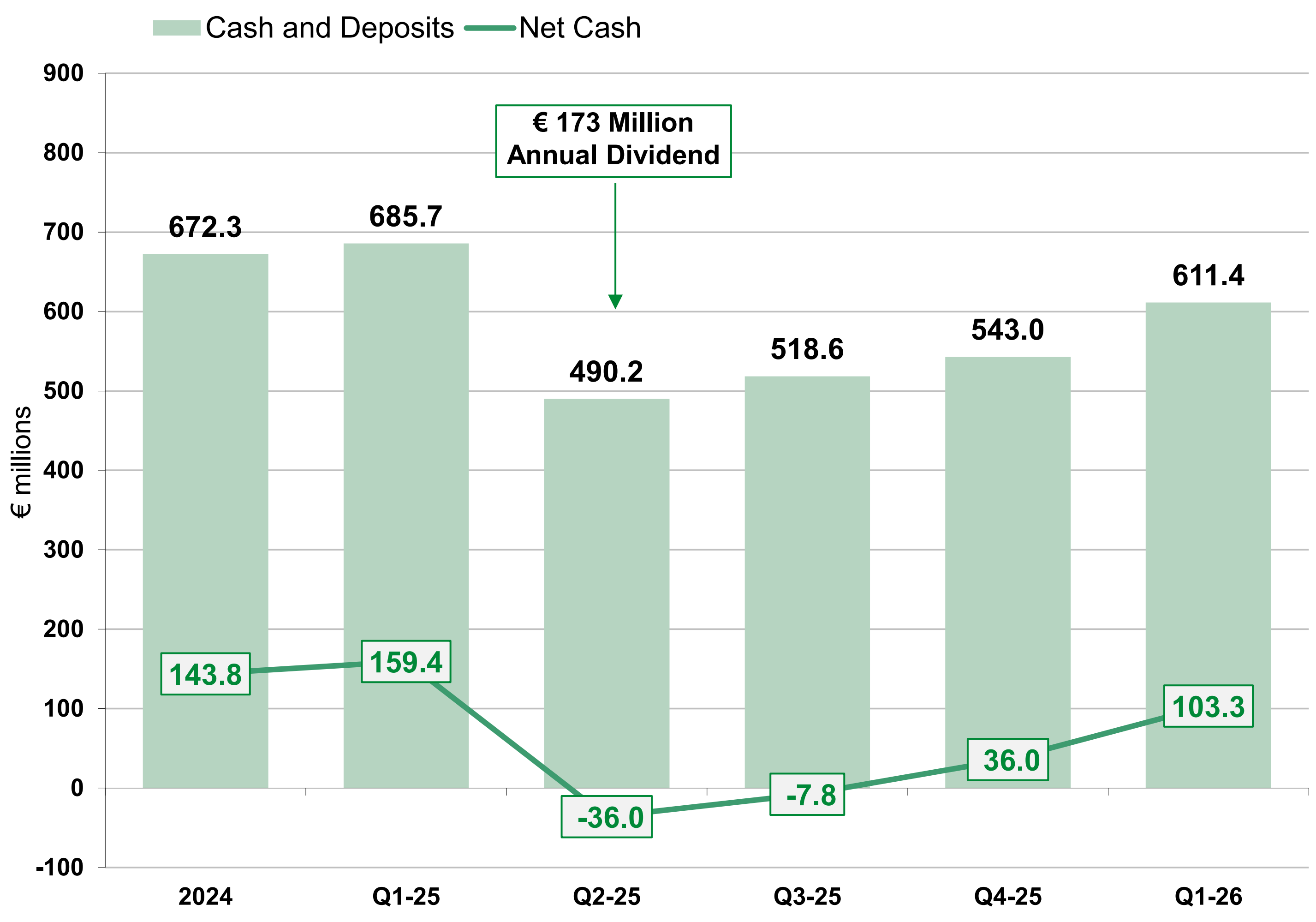
* As compared to Q4-25

Favorable Revenue and Profit Growth Sequentially and Year Over Year





Solid Q1-26 Cash Flow Generation. Net Cash Position Improving



Q1-26 vs. Q4-25

- Cash and deposits of € 611.4 million
  - + € 68.4 million primarily due to:
    - + € 93.0 million cash flow from operations
    - - € 14.2 million share repurchases
    - - € 6.8 million capex and capitalized R&D
- Net cash of € 103.3 million
  - + € 67.3 million sequentially

Debt outstanding

- € 175 million 1.875% Convertible Notes due 2029
- € 350 million 4.5% Senior Notes due 2031

II. MARKET & STRATEGY

Assembly Market Trends

TechInsights forecasts renewed assembly growth

- 21% increase anticipated in 2026
- 75% increase expected 2025-2030
  - Expansion of AI/use cases
  - Recovery of mainstream applications
  - New fabs coming online
- Broad based advanced packaging growth expected

Besi expects to significantly outperform projected assembly market growth

Source: TechInsights, March 2026. Assembly equipment revenue excludes service revenue

Strategic Update

- ✓ Order momentum continues for 2.5D and 3D AI applications
- ✓ Hybrid bonding adoption continues to expand
- ✓ Higher orders for hybrid bonding in logic, co packaged optics and HBM applications
- ✓ Recovery in mobile and automotive end-user markets
- ✓ Aligning organization and supply chain for increased order outlook
- ✓ Developing additional Vietnamese production capacity for mainstream assembly applications
- ✓ Increasing service and support efforts in Taiwan and Korea in anticipation of increased hybrid bonding activities

Increased Hybrid Bonding Use Cases and Products in the News

TSMC	"TSMC says COUPE platform set for production as Samsung outlines Silicon Photonics push" *Digitimes Asia. April 2026* "Taiwan's TSMC advanced packaging fabs on schedule" TSMC is expanding its advanced packaging capacity, especially SoIC hybrid bonding, which enables 3D stacking. *Taiwan News. March 2026*
Broadcom	"Semiconductor Equipment's Next Gold Mine" Broadcom XDSiP 3.5D platform's core feature is hybrid copper bonding *36Kr Europe. March 2026* "Broadcom paves path for the 200T AI Era" Broadcom highlights optical roadmap, including co-packaged optics and photonics enabled scaling for future AI networks. *Broadcom. March 2026*
SK hynix	"Hybrid bonding expands from logic to memory: SK Hynix, Applied Materials, Besi drive co-optimization to scale next-gen HBM" *Counterpoint. April 2026* "SK Hynix eyes hybrid bonding for HBM5 launch by 2029" *Counterpoint. April 2026*
NVIDIA	"NVIDIA Rubin Ultra and Feynman reportedly to boost TSMC SoIC; Besi, Applied Materials, TEL to benefit" *Trendforce. March 2026* "NVIDIA Feynman GPU gets 3D die-stacking, custom HBM & Next gen Rosa CPU" *Wccftech. March 2026*
Samsung	"Samsung, SK Hynix reportedly ramp hybrid bonding push for next-gen HBM" *Digitimes Asia. April 2026* "Samsung unveils HBM4E, showcasing comprehensive AI solutions, NVIDIA partnership and Vision at NVIDIA GTC 2026" *Samsung. March 2026* "Samsung Electronics launches silicon photonics foundry business." Building production ready photonic integrated circuits now with aim to scale toward co-packaged optics by 2030" *Design & Reuse. April 2026*
Micron	"How Micron is Looking to Win the HBM Wars" Micron frames hybrid bonding as part of its 2026 HBM4 transition. *Forbes. April 2026*
Apple	"Apple M5 Pro and M5 Max to feature 3D hybrid bonding". *Netfox. March 2026*
Coherent	"Coherent demonstrates multiple co-packaged optics technologies at OFC 2026." Coherent to show how photonics stack can meet bandwidth and efficiency needs of AI datacenters. *Coherent. March 2026*
AMD	"Engineering the Future of AI" AMD has ongoing innovation in 2.5D, 3D and hybrid bonding as part of heterogeneous packaging for future Instinct accelerators *AMD Blog. November 2025*

III. OUTLOOK

Guidance Q2-26 & H1-26

Besi

€ in millions

Q2-26

	Q1-26	Q2-26
Revenue	€ 184.9	+30% to +40%
Gross Margin	63.5%	64%-66%
Total Operating Expenses	€ 53.5	0% to +10%

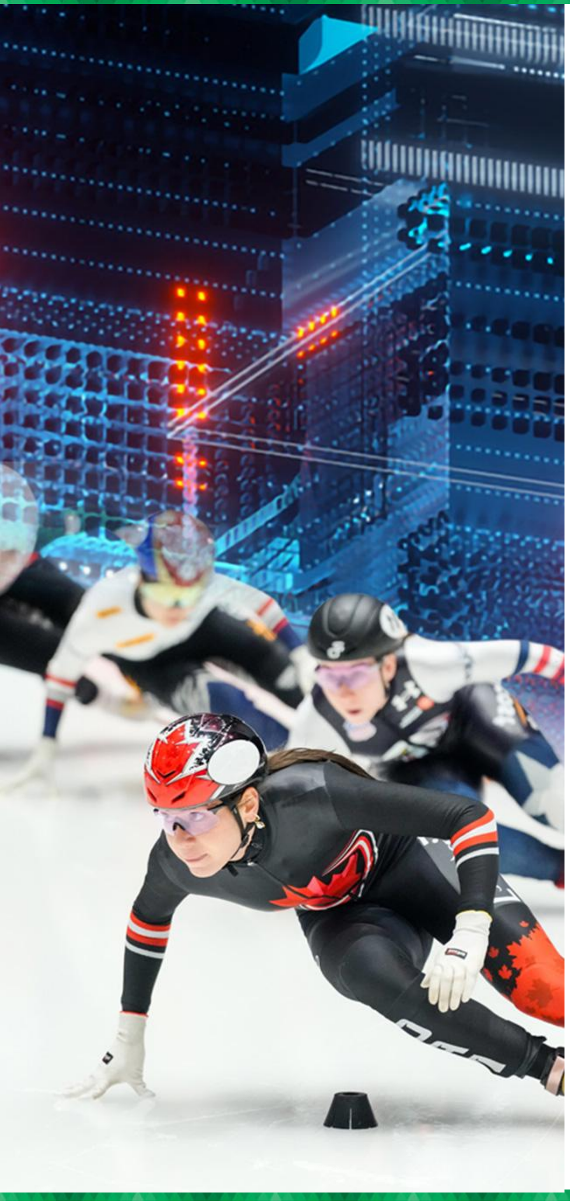
HY1-26

	HY1-25	HY1-26*
Revenue	€ 292.2	+49%
Gross Margin	63.4%	~64.4%
Total Operating Expenses	€ 102.7	+7%

* At midpoint of Q2-26 guidance

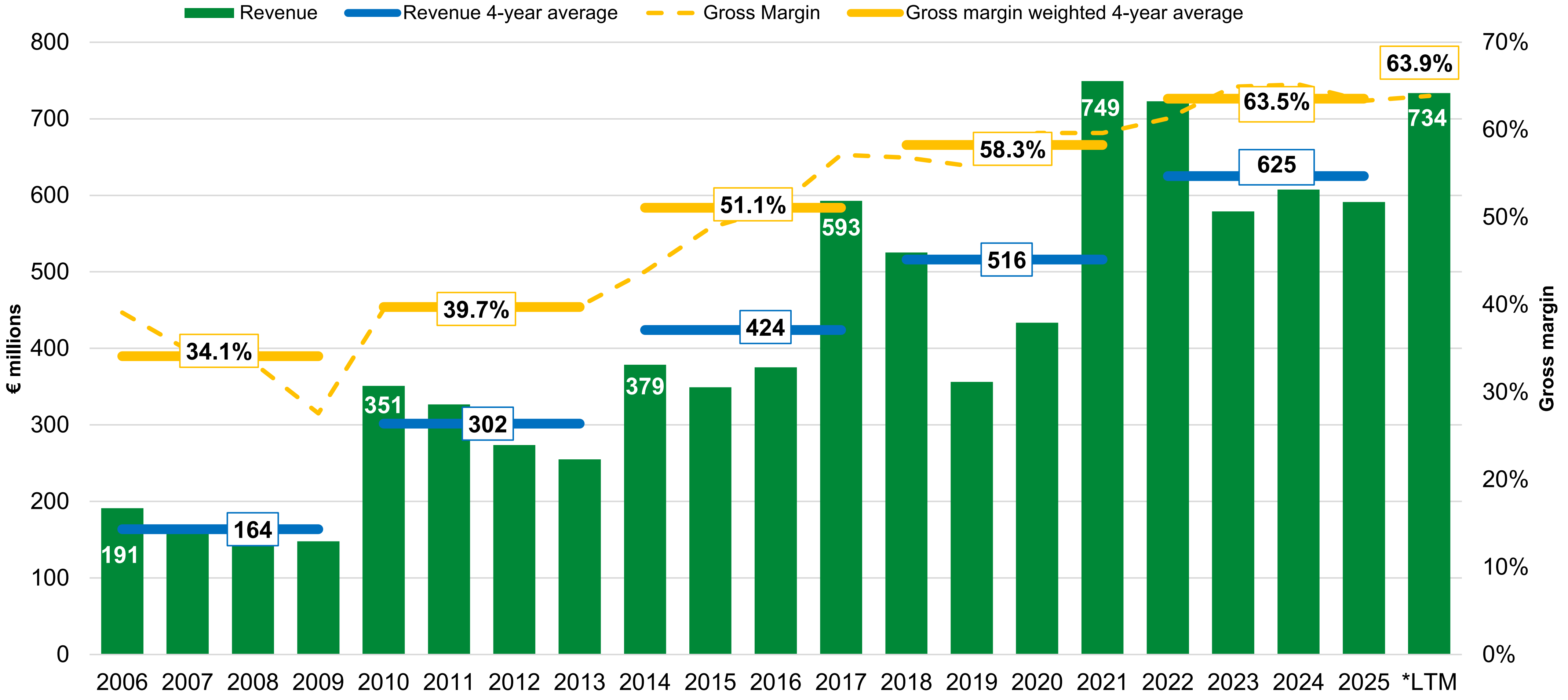
Financial Calendar 2026

23 Apr 2026	Besi’s Annual General Meeting of Shareholders, Duiven
13 May 2026	UBS Best of Europe Virtual One-on-One Conference
19 May 2026	Imec ITF World, Antwerp
20 May 2026	Berenberg European Conference, New York
21 May 2026	J.P Morgan European TMT Conference, London
27 May 2026	TD Cowen’s TMT Conference, New York
28 May 2026	Bernstein Conference, New York
4 Jun 2026	BNP Paribas CEO Conference, Paris
18 Jun 2026	Besi Investor Day, Amsterdam
23 Jul 2026	Besi’s Q2-2026 results
22 Oct 2026	Besi’s Q3-2026 results



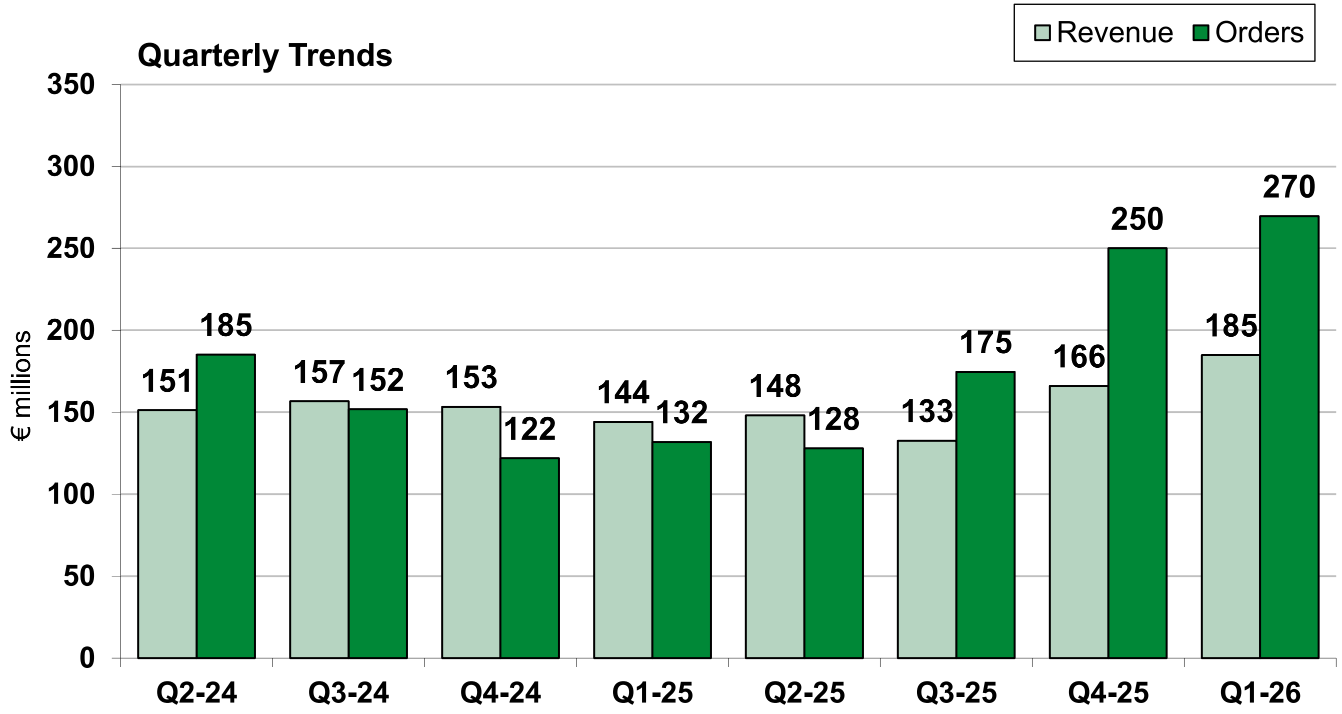
IV. FINANCIAL APPENDIX

Through Cycle Revenue and Gross Margin Trends



* At midpoint of Q2-26 guidance

Revenue/Order Trends

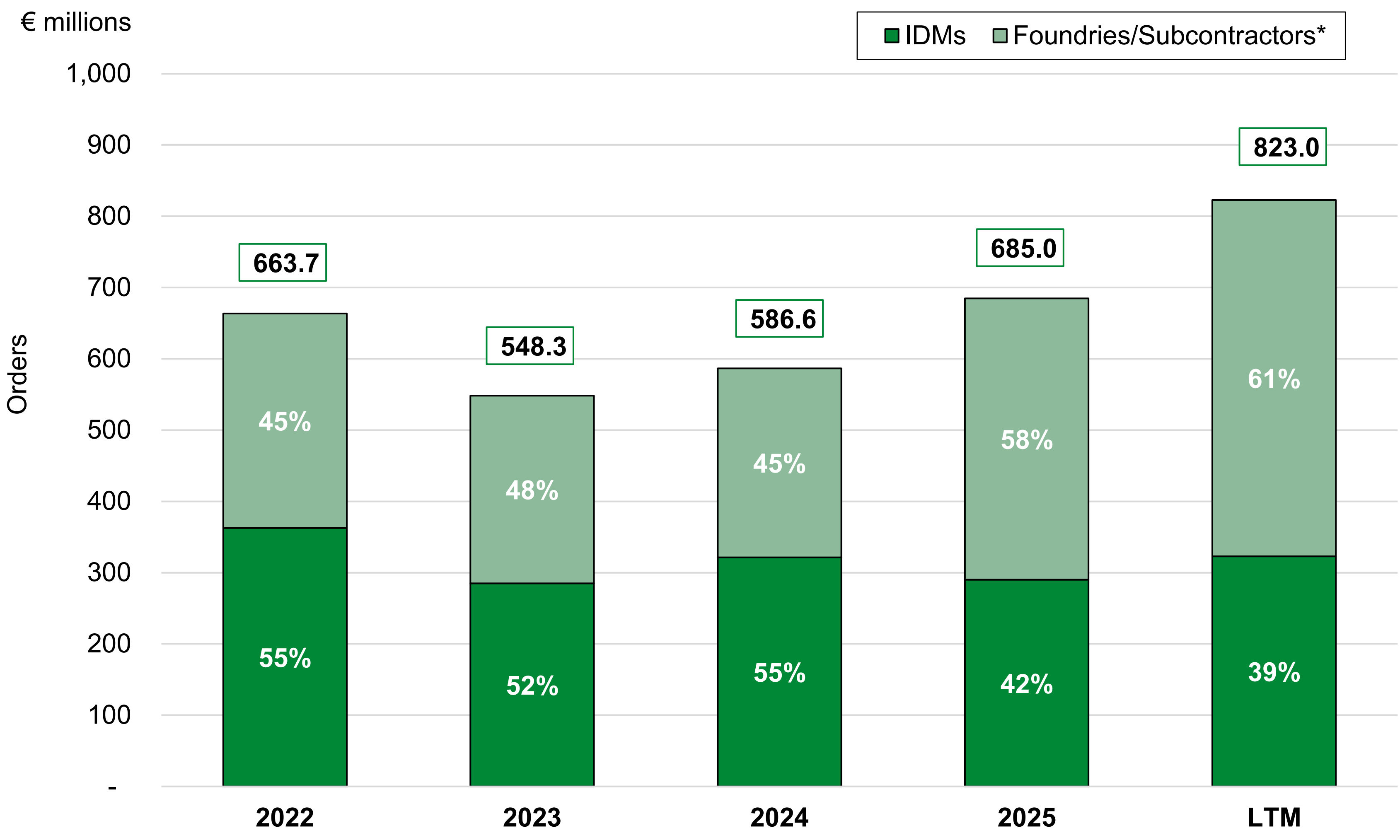


Book/Bill	1.2x	1.0x	0.8x	0.9x	0.9x	1.3x	1.5x	1.5x

<u>Q1-26 vs. Q4-25</u>
- **Revenue: +€ 18.5 million (+11.1%)**
  - Above midpoint of guidance
  - Higher mobile, 2.5D AI-related computing and photonics
  - Partial offset: lower automotive revenue
- **Orders: +€ 19.3 million (+7.7%)**
  - Strong hybrid bonding growth

<u>Q1-26 vs. Q1-25</u>
- **Revenue: +€ 40.8 million (+28.3%)**
- **Orders: +€ 137.8 million (+104.5%)**
  - Growth across all end user markets
  - Particular strength in hybrid bonding, mobile and photonics applications

Order Trends

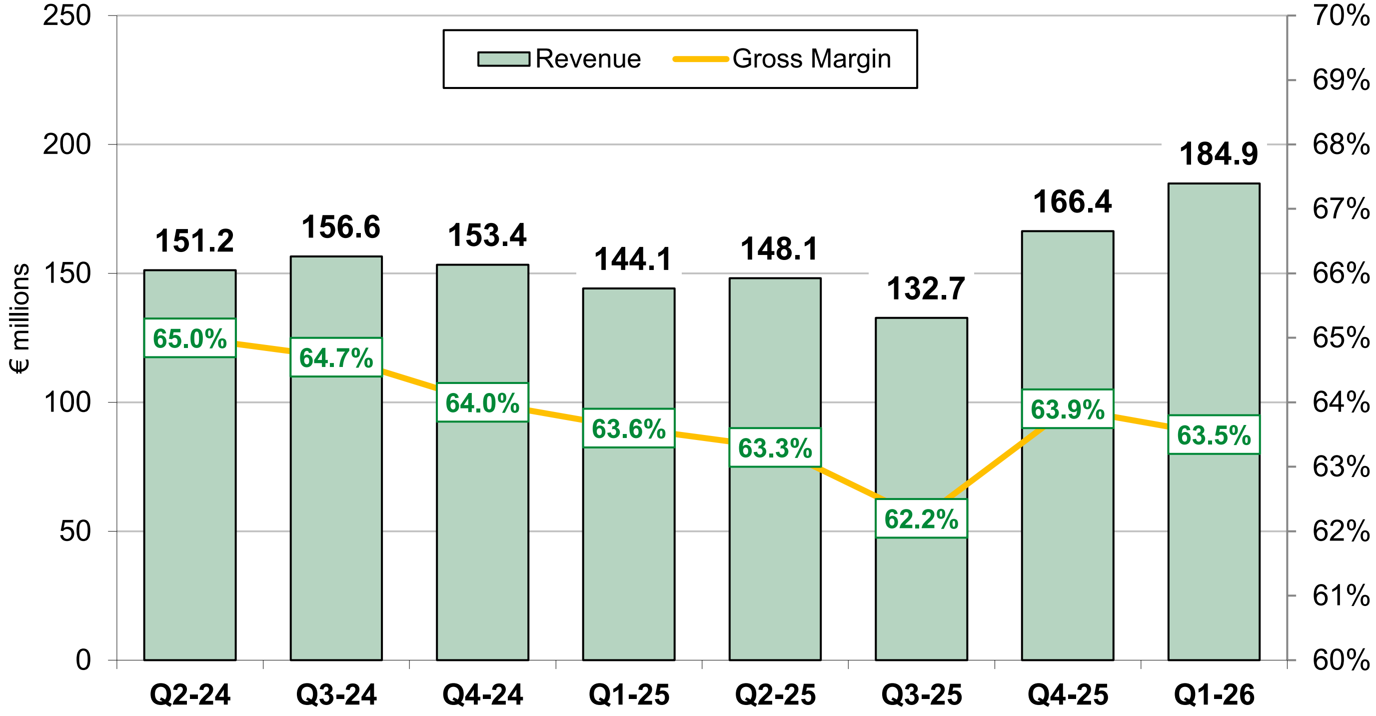


* Includes foundries and subcontractors as of 2024

Gross Margin Trends

Besi

Quarterly Trends



Q1-26 vs. Q4-25

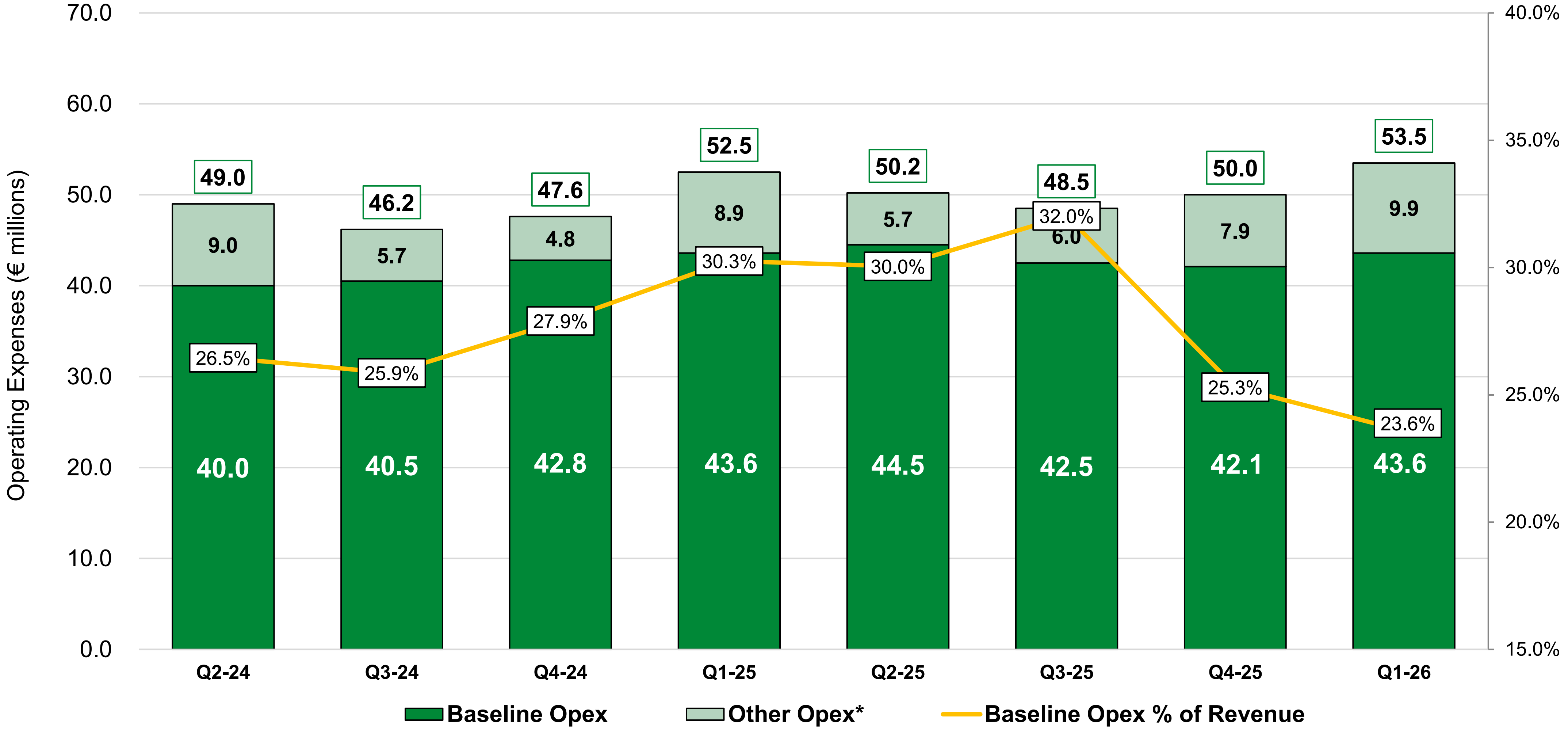
- **63.5% vs. 63.9% (-0.4 points)**
  - In line with guidance
  - Net forex negative: Revenue - USD vs. EUR
    Costs - MYR/RMB vs. EUR

Q1-26 vs. Q1-25

- **63.5% vs. 63.6% (-0.1 points)**
  - Net forex negative: Revenue - USD vs. EUR
    Costs - MYR vs. EUR

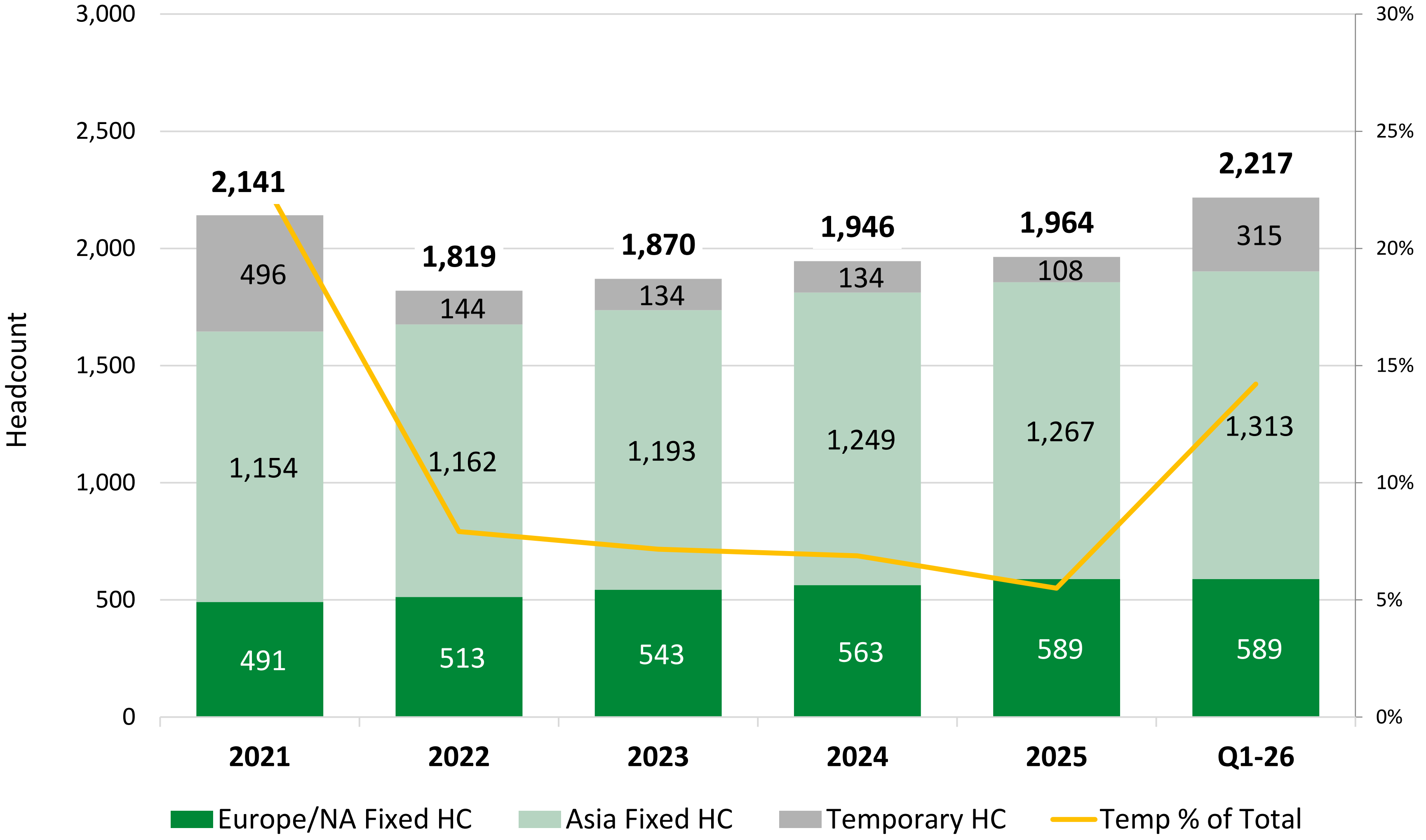
* Favorable impact
Unfavorable impact

Baseline Operating Expense Trends



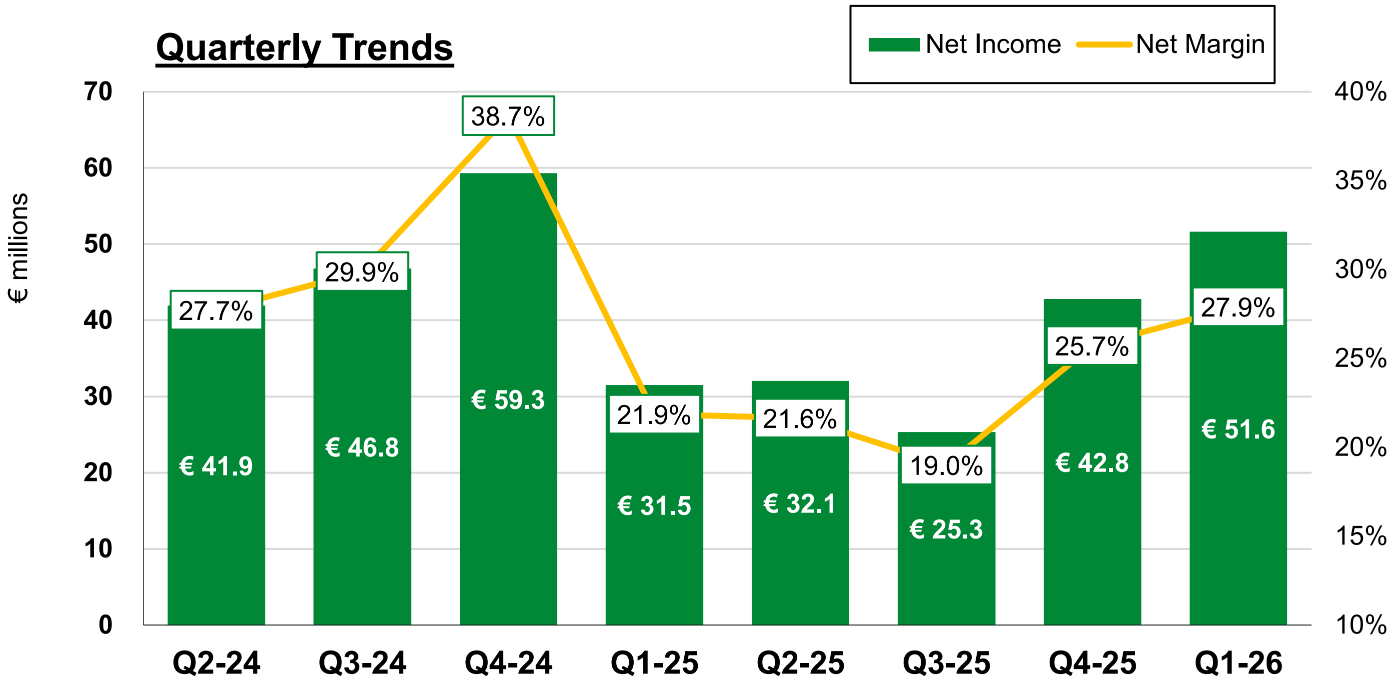
* Other Opex includes both short-term and long-term incentive compensation, restructuring costs, net R&D capitalization/amortization and certain one-time items including strategic consulting costs.

Headcount Trends



Increasing Asian fixed and temporary headcount to support order upturn and increased hybrid bonding activities

Net Income Trends



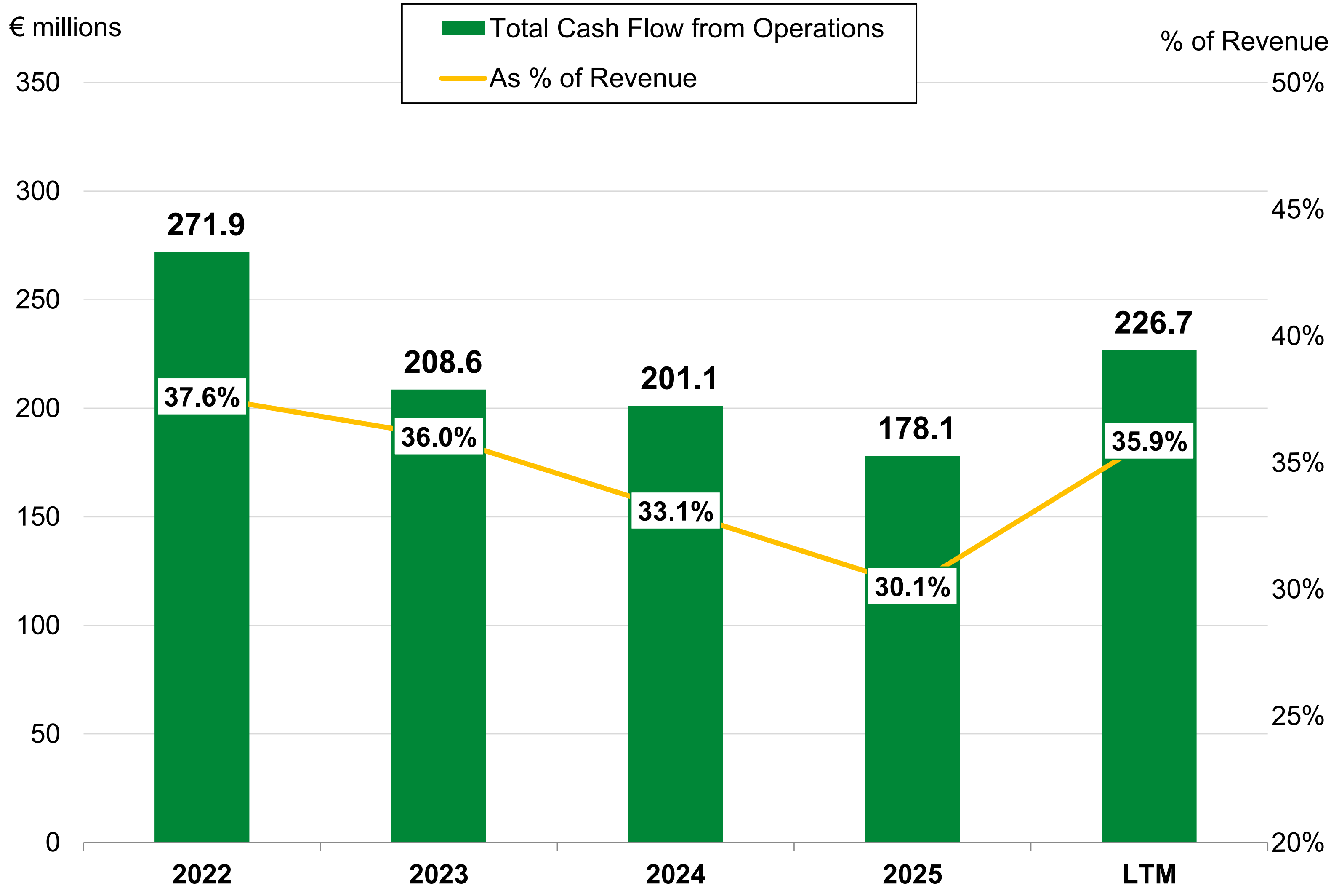
Q1-26 vs. Q4-25

- **€ 51.6 million (+€ 8.8 million)**
  - +11.1% higher revenue
- Partial offset:
  - -0.4 point lower gross margin
  - -€ 1.6 million higher R&D
  - -€ 1.8 million higher SG&A, primarily share-based compensation expense

Q1-26 vs. Q1-25

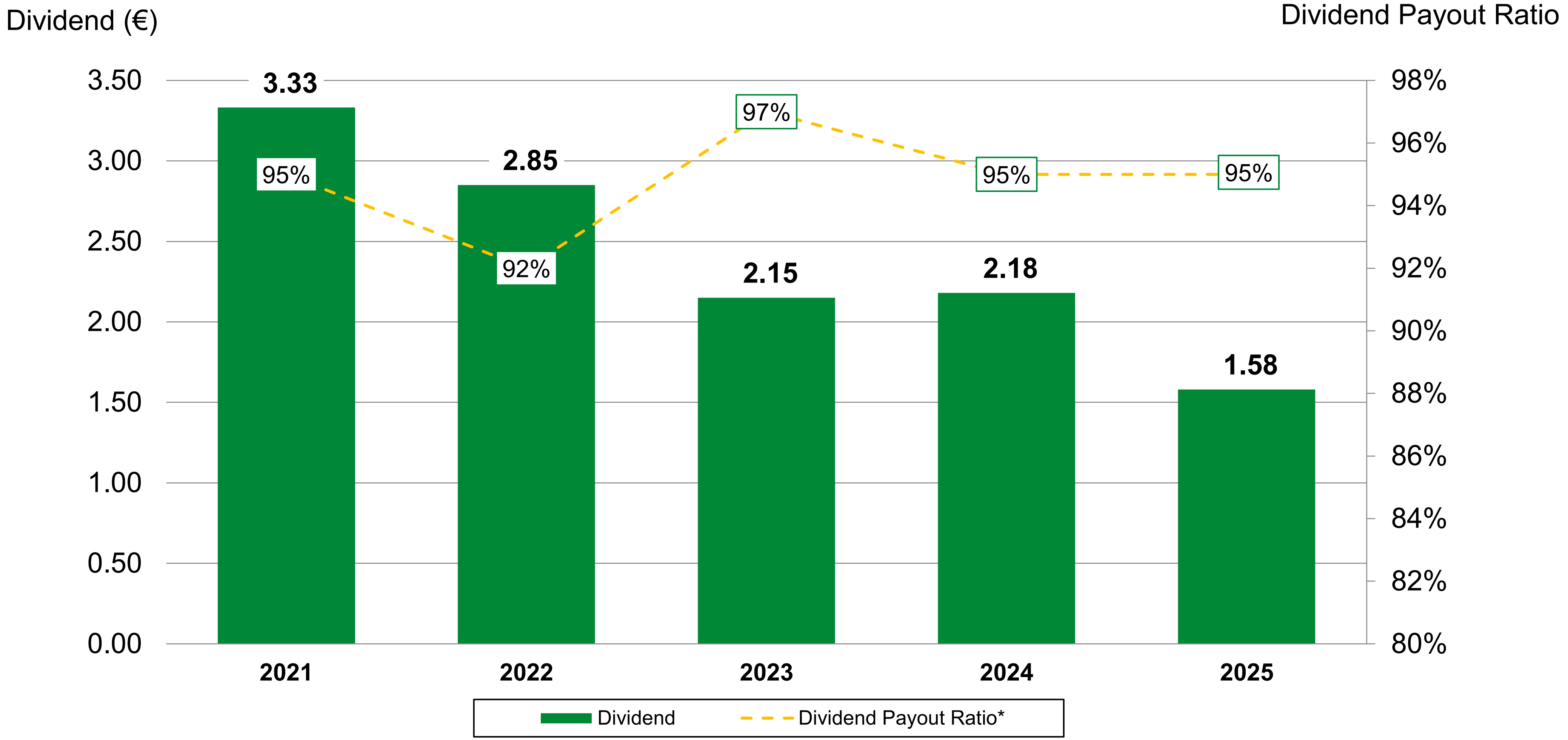
- **+€ 20.1 million**
  - +28.3% higher revenue
- Partial offset by:
  - -0.1 point lower gross margin
  - -€ 1.0 million higher OPEX

Cash Flow Efficiency Trends



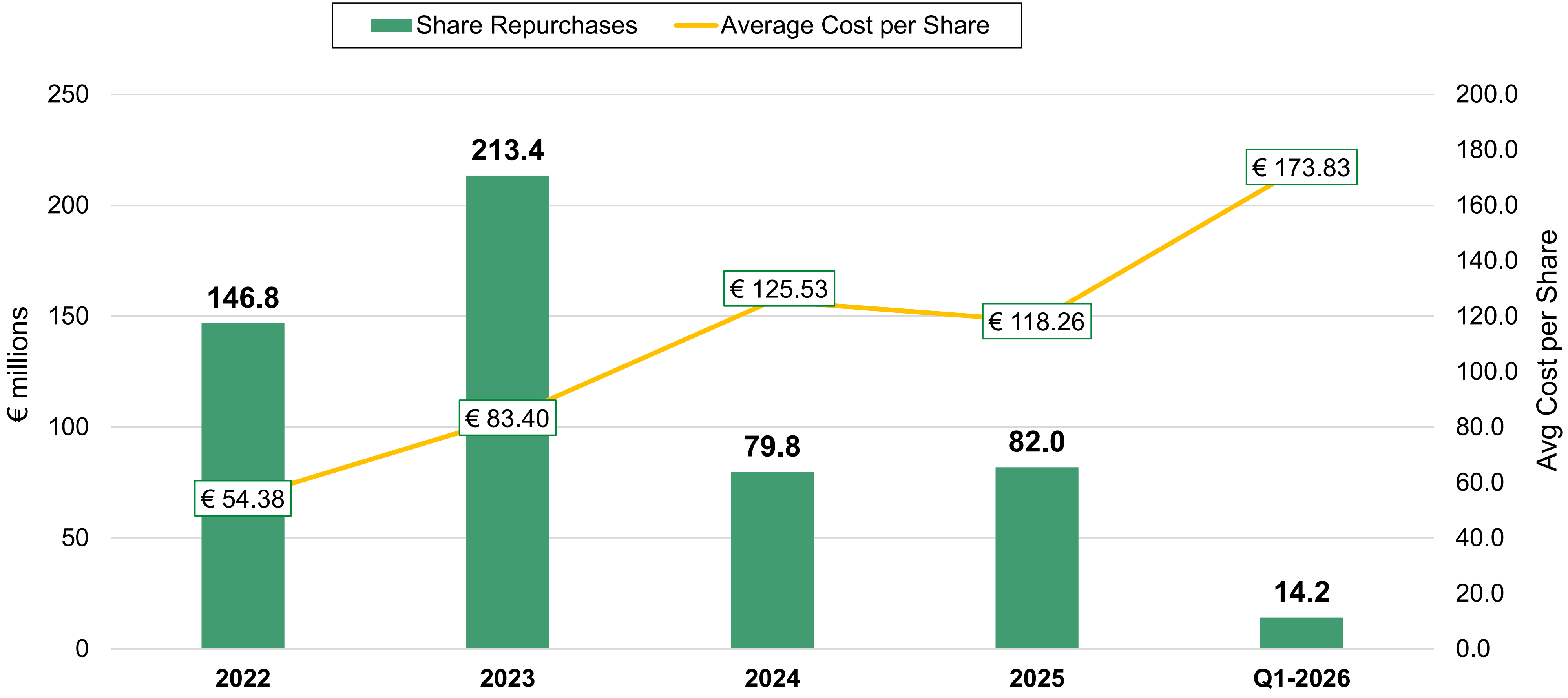
Dividend Trends

Cumulative dividends of € 1.7 billion since 2011, or € 21.54 per share*



* Calculated on Basic EPS. Includes value of both cash and stock dividends and dividend for approval at 2026 AGM

Share Repurchase Activity



- Approximately 1.9 million treasury shares at March 31, 2026, representing 2.4% of shares outstanding
- 79.2 million shares outstanding at March 31, 2026, net of treasury shares

Investment Considerations

Besi

Assembly market ever more critical in semiconductor value chain

Disciplined strategic focus has created an industry leader

Long term secular trends drive advanced packaging growth

Wafer level assembly for AI applications promising new growth opportunity

Market presence has grown via key IDMs, supply chains and partners

Tech leadership and scalability result in superior financial returns

Commitment to sustainable growth and fighting climate change

Attractive capital allocation policy